

WHAT IS CLAIMED IS:

1. A method for producing a wiring transfer sheet comprising a carrier base and a wiring layer formed on a surface of the carrier base, the method comprising:

superposing on a surface of the carrier base a sheet of a wiring material having a first rough surface so that the first rough surface contacts the surface of the carrier base;

forming on the surface of the carrier base a second rough surface complementary to the first rough surface of the sheet of the wiring material; and

forming a wiring layer with a predetermined wiring pattern on the surface of the carrier base by etching the sheet of wiring material.

2. The method according to claim 1, wherein the first rough surface is a surface having a plurality of convexities.

3. A method for producing a wiring transfer sheet comprising a carrier base and a wiring layer formed on a surface of the carrier base, the method comprising:

forming the wiring layer having a predetermined pattern on the surface of the carrier base; and

roughening an exposed area of the surface of the carrier base on which surface the wiring layer is formed, using a roughing treatment.

4. The method according to claim 3, wherein a plurality of concavities are formed on an exposed area of the surface of the carrier base by the roughing treatment.

5. A method for producing a wiring transfer sheet comprising a carrier base and a wiring layer formed on a surface of the carrier base, the method comprising forming the wiring layer by depositing a metal on a rough surface of the carrier base by metal plating.

6. The method according to claim 5, wherein the rough surface of the carrier base is a surface having a plurality of concavities.

7. A wiring transfer sheet produced according to the method of claim 1.